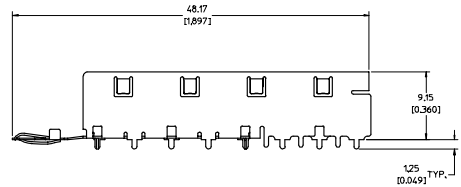
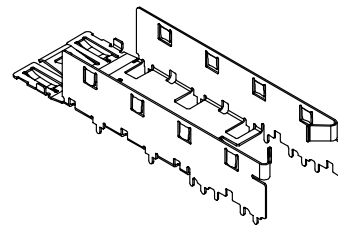
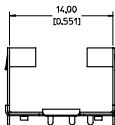
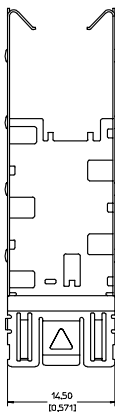


NOTES:

1. MATERIAL: COPPER ALLOY
2. PLATING: BRIGHT TIN
2.54 MICROMETERS TIN (MIN)
OVER 0.76 MICROMETERS (MIN) NICKEL
3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER TO DOCUMENT SD-73927-100.
4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, (RoHS), REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C
5. FOR RoHS COMPLIANT REPLACEMENTS REFER TO MOLEX SERIES 74737.

ENTER DESCRIPTION IEC NO. LIST 2004-0264 DRIVING MONSON 2006/07/03 CHROBRUSSELL 2006/07/04 APPROVED DESCRIPTION REF	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION																		
	$\nabla=0$ $\nabla=0$	<table border="1"> <tr> <th></th> <th>mm</th> <th>INCH</th> </tr> <tr> <td>4 PLACES</td> <td>± 0.13</td> <td>± 0.01</td> </tr> <tr> <td>3 PLACES</td> <td>± 0.05</td> <td>± 0.005</td> </tr> <tr> <td>2 PLACES</td> <td>± 0.13</td> <td>± 0.01</td> </tr> <tr> <td>1 PLACE</td> <td>± 0.25</td> <td>± 0.01</td> </tr> <tr> <td>ANGULAR</td> <td>$\pm 1^\circ$</td> <td></td> </tr> </table>		mm	INCH	4 PLACES	± 0.13	± 0.01	3 PLACES	± 0.05	± 0.005	2 PLACES	± 0.13	± 0.01	1 PLACE	± 0.25	± 0.01	ANGULAR	$\pm 1^\circ$		MM/IN DRAWN BY: KS MONSON CHECKED BY: BRUSSELL APPROVED BY: BRUSSELL DATE: 2005/10/12 DATE: 2005/10/12 DATE: 2005/10/12	4:1	METRIC	
		mm	INCH																					
	4 PLACES	± 0.13	± 0.01																					
3 PLACES	± 0.05	± 0.005																						
2 PLACES	± 0.13	± 0.01																						
1 PLACE	± 0.25	± 0.01																						
ANGULAR	$\pm 1^\circ$																							
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO: 739270040 SIZE: D	TITLE: SFP CAGE BASE SOLDER POSTS FOR WAVE SOLDER MOLEX INCORPORATED DOCUMENT NO: SD-73927-0040	SHEET NO: 1 OF 1																				
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION																								



NOTES:

1. MATERIAL: COPPER ALLOY
2. PLATING: BRIGHT TIN
2.54 MICROMETERS TIN (MIN)
OVER 0.76 MICROMETERS (MIN) NICKEL
3. FOR DETAILS OF PCB AND BEZEL LAYOUT REFER TO DOCUMENT SD-73927-100.
4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C. FOR REFLOW PROCESSES GREATER THAN 180°C, REFER TO MOLEX SERIES 74737.

ENTER DESCRIPTION EC NO. 2006/07/29 DRAWN BY EP DRINKS/COX CHKD BY CHRIS APPROVED BY J.P. BRUSSELL DATE 2005/10/12	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	4:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
		3 PLACES ± --- ± 0.05	KS MONSON 2005/10/12	SFP CAGE BASE SOLDER POSTS FOR WAVE SOLDER		
	2 PLACES ± 0.13 ± 0.1	CHECKED BY DATE	MOLEX INCORPORATED			
	1 PLACE ± 0.25 ± ---	APPROVED BY DATE	MOLEX INCORPORATED			
	ANGULAR ± 1 °	BRUSSELL 2005/10/12	MOLEX INCORPORATED			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		PARTIAL NO.	739270040	DOCUMENT NO.	SD-73927-040	
		SIZE	D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		